



#### **60V P-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

V <sub>(BR)DSS</sub>	Max R <sub>DS(on)</sub>	Max I <sub>D</sub> T <sub>A</sub> = +25°C		
-60V	400mΩ @ V <sub>GS</sub> = -10V	-1.1A		
	600mΩ @ V <sub>GS</sub> = -4.5V	-0.9A		

### **Description**

This MOSFET utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed, making it ideal for high-efficiency power management applications.

### **Applications**

- DC-DC Converters
- Power Management Functions
- · Relay and Solenoid Driving
- Motor Control

#### **Features**

- · Fast switching speed
- · Low input capacitance
- Low gate charge
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

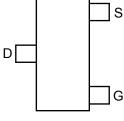
#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.008 grams (approximate)

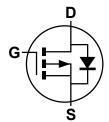




Top View



Top View Pin Out



**Equivalent Circuit** 

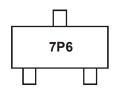
### **Ordering Information** (Notes 4)

Product	Compliance	Case	Packaging
ZXMP6A13FTA	Standard	SOT23	3,000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



7P6 = Product Type Marking Code



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units	
Drain-Source Voltage			$V_{DSS}$	-60	V	
Gate-Source Voltage			$V_{GS}$	±20	V	
Continuous Drain Current	V <sub>GS</sub> = -10V	T <sub>A</sub> = +70°C	(Note 7) (Note 7) (Note 6)	I <sub>D</sub>	-1.1 -0.8 -0.9	А
Pulsed Drain Current (Note 7)			$I_{DM}$	-4	A	
Continuous Source Current (Body Diode) (Note 6)			Is	-1.2	Α	
Pulsed Source Current (Body Diode) (Note 7)			I <sub>SM</sub>	-4	A	

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	В	625	mW
Linear Derating Factor	P <sub>D</sub>	5	mW/°C
Power Dissipation (Note 6)	В	806	mW
Linear Derating Factor	P <sub>D</sub>	6.5	mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	200	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	155	°C/W
Thermal Resistance, Junction to Leads (Note 8)	R <sub>0JL</sub>	194	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

Notes:

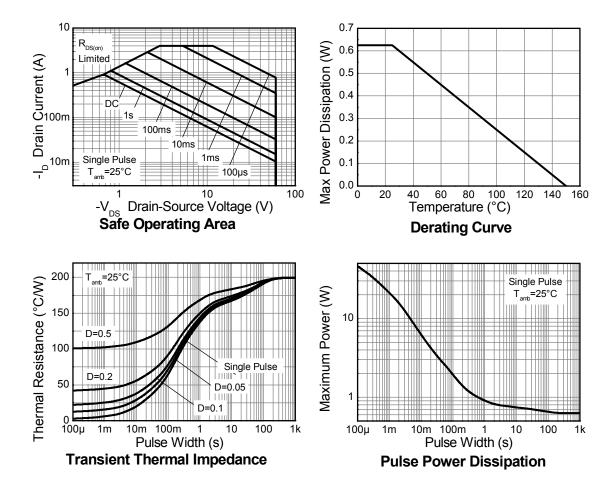
- 5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions 6. For a device surface mounted on FR4 PCB measured at t ≤ 5secs.

  7. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05 pulse width = 10μs pulse current limited by maximum junction temperature.

  8. Thermal resistance from junction to solder-point (at the end of the collector lead).



# **Thermal Characteristics**





# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

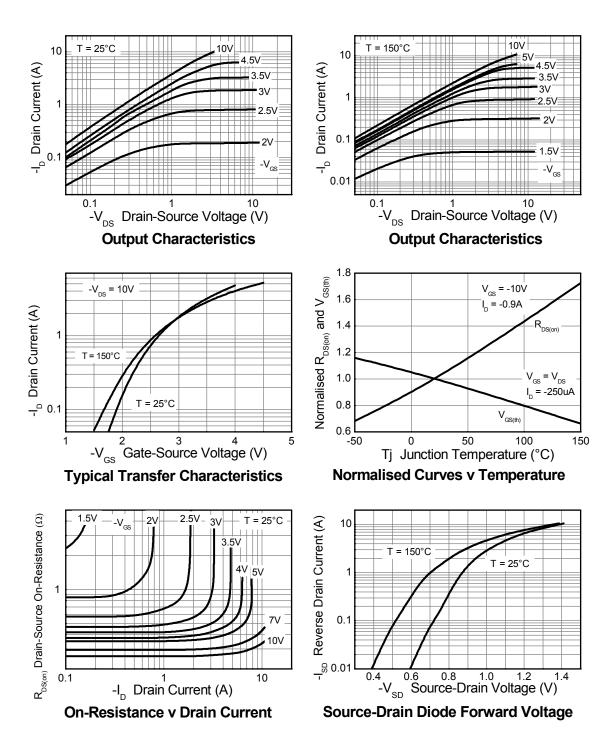
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-60	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	-0.5	μΑ	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(th)}$	-1	_	-3	٧	$I_D = -250 \mu A$ , $V_{DS} = V_{GS}$	
Static Drain-Source On-Resistance (Note 9)	P== (0.1)			0.400	Ω	$V_{GS} = -10V, I_D = -0.9A$	
Static Drain-Source Off-Resistance (Note 9)	R <sub>DS (ON)</sub>		_	0.600	32	$V_{GS} = -4.5V$ , $I_D = -0.8A$	
Forward Transconductance (Notes 9 & 11)	<b>g</b> fs		1.8	_	S	$V_{DS} = -15V$ , $I_{D} = -0.9A$	
Diode Forward Voltage (Note 9)	$V_{SD}$	_	-0.85	-0.95	V	$T_J = +25^{\circ}C$ , $I_S = -0.8A$ , $V_{GS} = 0V$	
Reverse Recovery Time (Note 11)	t <sub>rr</sub>	_	21.1	_	ns	$T_J = +25^{\circ}C, I_F = -0.9A,$	
Reverse Recovery Charge (Note 11)	Q <sub>rr</sub>	_	19.3	_	nC	di/dt = 100A/μs	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C <sub>iss</sub>	_	219	_			
Output Capacitance	Coss		25.7	_	pF	$V_{DS} = -30V, V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		20.5	_			
Turn-On Delay Time (Note 10)	t <sub>D(on)</sub>	_	1.6	_			
Turn-On Rise Time (Note 10)	t <sub>r</sub>	_	2.2	_		$V_{DD}$ = -30V, $I_D$ = -1A, $R_G \cong 6.0\Omega$ , $V_{GS}$ = -10V	
Turn-Off Delay Time (Note 10)	t <sub>D(off)</sub>	_	11.2	_	ns		
Turn-Off Fall Time (Note 10)	t <sub>f</sub>	_	5.7	_			
Total Gate Charge (Note 10)	Qg	_	2.9	_	nC	$V_{DS} = -30V$ , $V_{GS} = -4.5V$ , $I_{D} = -0.9A$	
Total Gate Charge (Note 10)	Qg	_	5.9	_		V <sub>DS</sub> = -30V, V <sub>GS</sub> = -10V,	
Gate-Source Charge (Note 10)	Q <sub>gs</sub>	_	0.74		nC		
Gate-Drain Charge (Note 10)	$Q_{gd}$		1.5			$I_D = -0.9A$	

Notes:

<sup>9.</sup> Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
10. Switching characteristics are independent of operating junction temperature.
11. For design aid only, not subject to production testing.

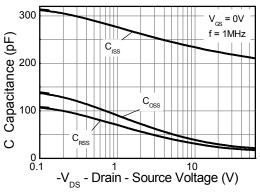


# **Typical Characteristics**

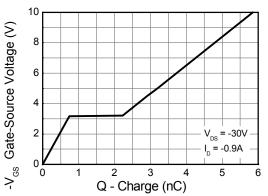




# Typical Characteristics - (cont.)

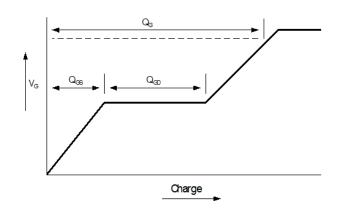


Capacitance v Drain-Source Voltage

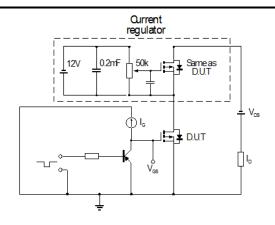


Gate-Source Voltage v Gate Charge

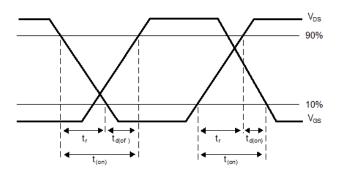
# **Test Circuits**



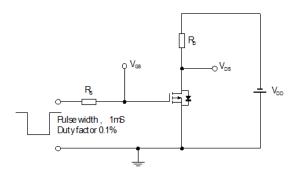
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

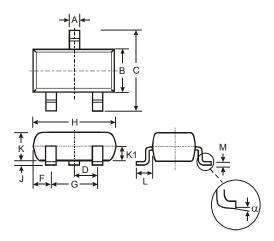


Switching time test circuit



# **Package Outline Dimensions**

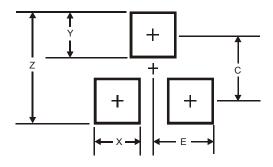
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.903	1.10	1.00		
K1	-	1	0.400		
L	0.45	0.61	0.55		
M	0.085	0.18	0.11		
α	0°	8°	-		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	2.9		
X	0.8		
Y	0.9		
С	2.0		
Е	1.35		



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